3.2x1.6mm SMD CHIP LED LAMP

Part Number: KPTL-3216SURCK Hyper Red

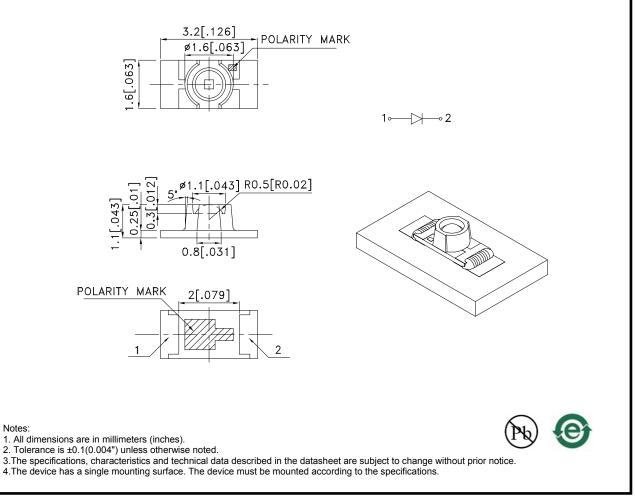
Features

- 3.2mmx1.6mm SMT LED, 1.1mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Hyper Red source color devices are made with Al-GalnP on GaAs substrate Light Emitting Diode.

Package Dimensions



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Selection Guide

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Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KPTL-3216SURCK	Hyper Red (AlGaInP)	WATER CLEAR	280	550	70°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Hyper Red	650		nm	I⊧=20mA	
λD [1]	Dominant Wavelength	Hyper Red	630		nm	I⊧=20mA	
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA	
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Hyper Red	1.95	2.5	V	IF=20mA	
lr	Reverse Current	Hyper Red		10	uA	VR=5V	

Notes:

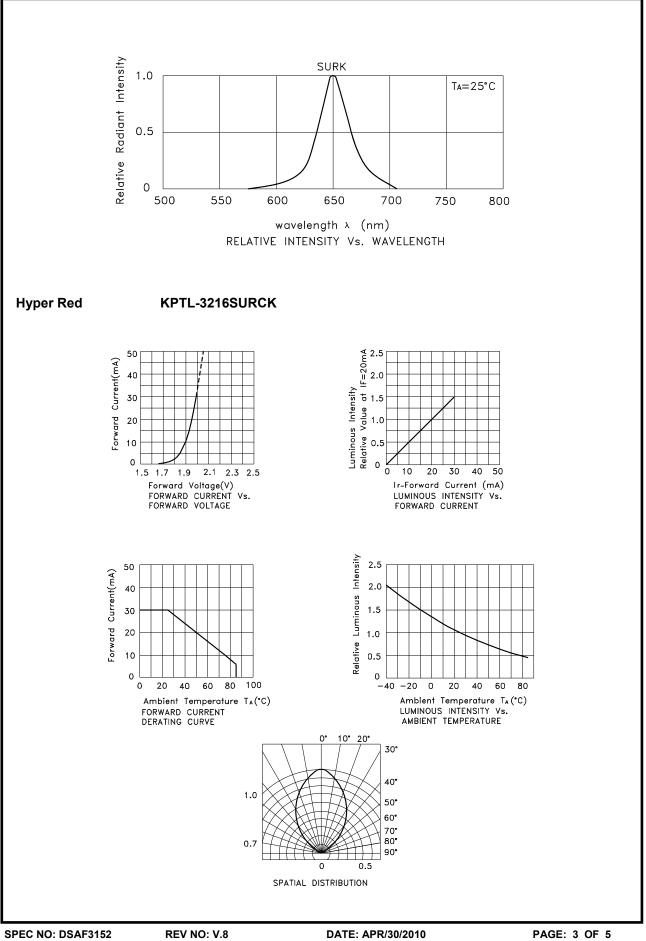
1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	185	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

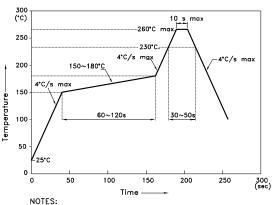
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



KPTL-3216SURCK

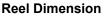
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

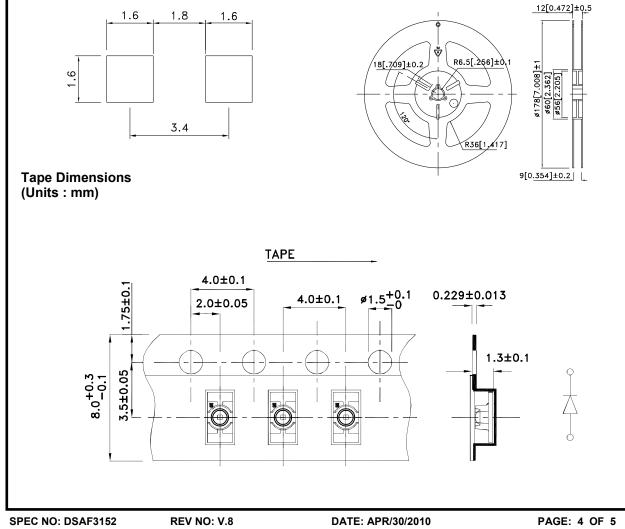
Reflow Soldering Profile For Lead-free SMT Process.



NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.







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